2.2x1.4mm SURFACE MOUNT LED LAMP

Part Number: KA-2214SURSK Hyper Red

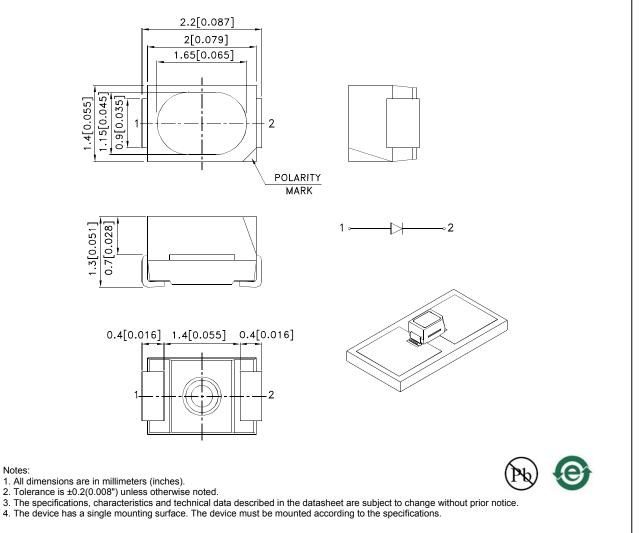
Features

- 2.2mm x 1.4mm, 1.3mm high.
- Low power consumption.
- Available on tape and reel.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red source color devices are made with Al-GalnP on GaAs substrate Light Emitting Diode.

Package Dimensions

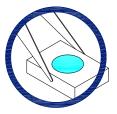


SPEC NO: DSAK1879 APPROVED: WYNEC REV NO: V.2 CHECKED: Allen Liu DATE: SEP/27/2010 DRAWN: Y.F.Lv PAGE: 1 OF 6 ERP: 1201005725

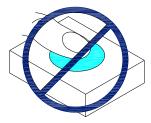
Handling Precautions

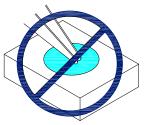
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

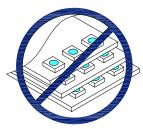


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





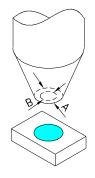
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4.1. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.

4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.

4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

DATE: SEP/27/2010 DRAWN: Y.F.Lv

Selection Guide

| Selection Guide | | | | | |
|-----------------|---------------------|-------------|------------------------|------|----------------------|
| Part No. | Dice | Lens Type | lv (mcd) [2] @ 20mA | | Viewing Angle [1] |
| | | | Min. | Тур. | 201/2 |
| KA-2214SURSK | Hyper Red (AlGaInP) | Water Clear | 180 | 350 | 120° |

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|-----------|------|------|-------|-----------------|
| λpeak | Peak Wavelength | Hyper Red | 650 | | nm | I⊧=20mA |
| λD [1] | Dominant Wavelength | Hyper Red | 630 | | nm | I⊧=20mA |
| Δλ1/2 | Spectral Line Half-width | Hyper Red | 28 | | nm | I⊧=20mA |
| С | Capacitance | Hyper Red | 35 | | pF | VF=0V;f=1MHz |
| VF [2] | Forward Voltage | Hyper Red | 1.95 | 2.5 | V | I⊧=20mA |
| lr | Reverse Current | Hyper Red | | 10 | uA | Vr=5V |

Notes:

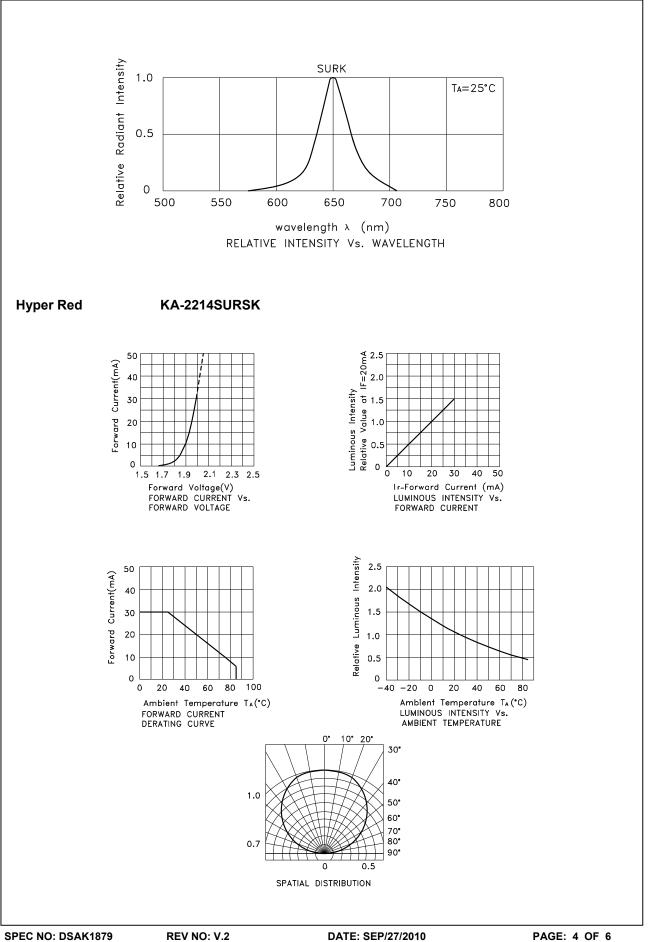
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

| Parameter | Hyper Red | Units | | |
|--------------------------|----------------|-------|--|--|
| Power dissipation | 75 | mW | | |
| DC Forward Current | 30 | mA | | |
| Peak Forward Current [1] | 185 | mA | | |
| Reverse Voltage | 5 | V | | |
| Operating Temperature | -40°C To +85°C | | | |
| Storage Temperature | -40°C To +85°C | | | |

Note:

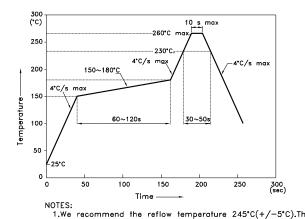
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



KA-2214SURSK

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed

to high temperature. 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

Reel Dimension

